/ Descriptions

Surface Mount Ultrafast Recovery Rectifier,Reverse Voltage:50 to1000V,Forward Current:1.0A, SMB package.

/ Features

Glass Passivated Chip Junction　High efficiency　Lead free in comply with EU R0HS 2011/65/EU directives　For surface mounted applications. Halogen free product.

/ Applications

General purpose.

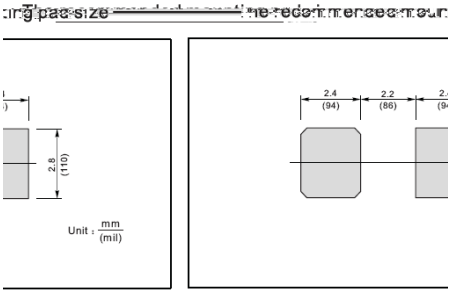
/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode



/ Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating							Unit
		US1AB	US1BB	US1DB	US1GB	US1JB	US1KB	US1MB	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at Tc = 125	$I_{F\ AV}$	1.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30							A
Typical Thermal Resistance(1)	$R_{\theta JA}$	75							/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~+150							

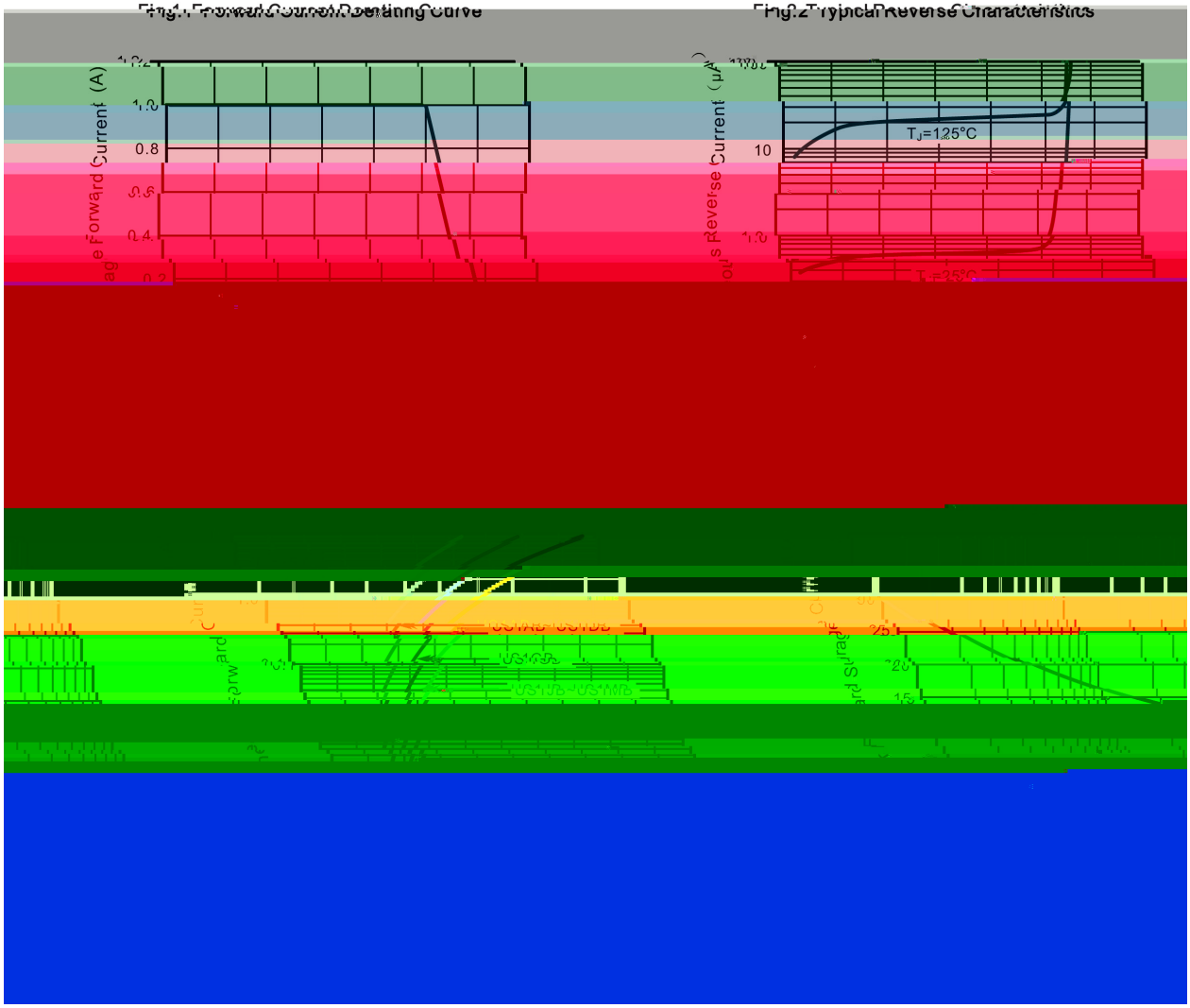
Note:

(1) P.C.B. mounted with 2.0 X 2.0" (5 X 5 cm) copper pad areass .

/ Electrical Characteristics(Ta=25)

Parameter	Symbol	Test condition	Rating							Unit
			US1AB	US1BB	US1DB	US1GB	US1JB	US1KB	US1MB	
Maximum Instantaneous Forward Voltage	V_F	I_F=1.0A	1.0			1.3	1.65			V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25	5.0							uA
		T_a=125	100							
Maximum Reverse Recovery Time	T_{rr}	I_F=0.5A I_R=1.0A I_{rr}=0.25A	50				75			ns

/ Electrical Characteristic Curve

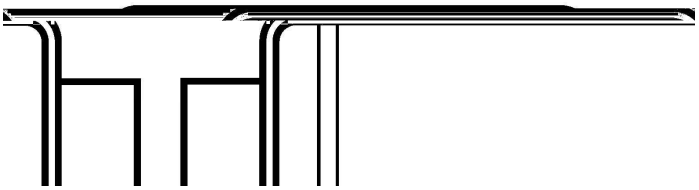


/ Package Dimensions

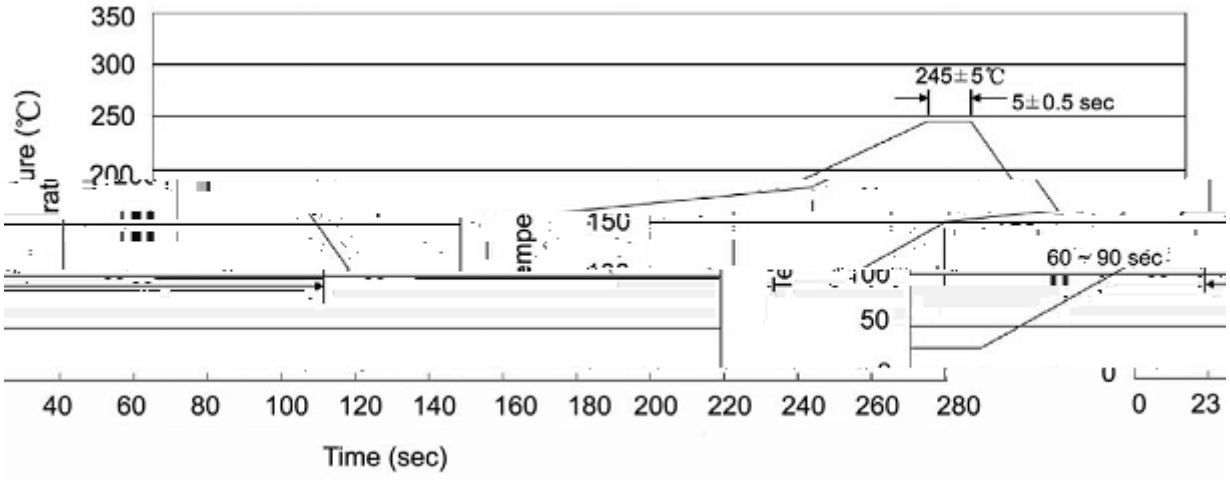
/ Marking Instructions

Marking

Type number	Marking code
US1AB	US1A
US1BB	US1B
US1DB	US1D
US1GB	US1G
US1JB	US1J
US1KB	US1K
US1MB	US1M



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



								Note:	
1		25	150		60	90sec;		1.Preheating:25~150	, Time:60~90sec.
2		245	5			5	0.5sec;	2.Peak Temp.:245	5 , Duration:5 0.5sec.
3				2	10	/sec.		3. Cooling Speed: 2~10	/sec.

/ Resistance to Soldering Heat Test Conditions

260	5	10	1 sec.	Temp.:260 5	Time:10 1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm^3)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMB	3000	5	15000	5	75000	7 ×11	185X180X105	390X385X205

/ Notices